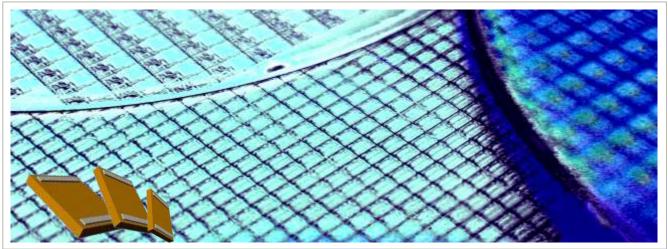


# HSSC424.xxx - 0402 High Stability Silicon Capacitor

Rev 3.0.1



#### **Key features**

- Ultra high stability :
  - ◆ Temperature ±0.5% (-55 °C to +150 °C)
  - Voltage <0.1 %/V</li>
  - ◆ Negligible aging <0.001% /10000hours
- Unique high capacitance in EIA/0402 package size, up to 100 nF
- High reliability (FIT <0.017 parts / billion hours)</p>
- Low leakage current < 100 pA</p>
- Low ESL and Low ESR
- Suitable with lead free reflow-soldering

Thanks to the unique IPDiA Silicon capacitor technology, most of the problems encountered in demanding application can be solved.

High Stability Silicon Capacitors are dedicated to applications where **stability** is the main parameter.

HSSC avoids the need to oversize the capacitor value for sensitive capacitive circuitry and offers a higher DC voltage stability.

This technology provides industry leading performances relative to the capacitor stability over the full operating voltage & temperature range.

The very high and stable insulation resistance of silicon capacitors can enhance up to 30 % the **battery lifetime** in mobile applications.

## **Key applications**

- All demanding applications, such as medical, aerospace, automotive industry
- High stability applications
- Decoupling / Filtering / Charge pump (i.e.: Pacemakers / defibrillators)
- Devices with battery operations
- Replacement of X7R and NP0 (COG)
- Downsizing

The IPDiA technology features a capacitor integration capability (up to 250nF/mm²) which allows a **smaller case size** than existing solutions to answer high volume constraints. This technology also offers **high reliability**, up to 10 times better than alternative capacitor technologies, such as Tantalum or MLCC, and eliminates cracking phenomena.

This Silicon based technology is RoHS compliant and compatible with lead free reflow soldering process.





# **Electrical specification**

		Capacitance value						
		10	15	22	33	47	68	
	,	10 pF:	15 pF:	22 pF:	33 pF:	47 pF:	68 pF:	
	1 pF	935.131.424.210	935.131.424.215	935.131.424.222	935.131.424.233	935.131.424.247	935.131.424.268	
Unit		100 pF:	150 pF:	220 pF:	330 pF:	470 pF:	680 pF:	
	10 pF	935.131.424.310	935.131.424.315	935.131.424.322	935.131.424.333	935.131.424.347	935.131.424.368	
		1 nF:	1.5 nF:	2.2 nF:	3.3 nF:	4.7 nF:	6.8 nF:	
	0.1 nF	935.131.424.410	935.131.424.415	935.131.424.422	935.131.424.433	935.131.424.447	935.131.424.468	
		10 nF:	15 nF:	22 nF:	33 nF:	47 nF:	Contact	
	1 nF	935.131.424.510	935.131.424.515	935.131.424.522	935.131.424.533	935.131.424.547	IPDIA Sales	
		100 nF:						
	10 nF	935.131.424.610						

(*) Thinner thickness	(as low as 100	um thick) available.	see Low Profile Silicon	Capacitor product: LPSC

(\*\*) Extended temperature range (up to +250 °C) available, see Xtreme Temperature Silicon Capacitor product: XTSC

(\*\*\*) Other values on request.

<u>Parameters</u>	<u>Value</u>		
Capacitance range	10 pF to 100 nF <sup>(***)</sup>		
Capacitance tolerances	±15 % <sup>(***)</sup>		
Operating temperature range	-55 °C to 150 °C (**)		
Storage temperatures	- 70 °C to 165 °C		
Temperature coefficient	±0.5 %, from -55 °C to +150 °C		
Breakdown voltage (BV)	11 VDC, 30VDC <sup>(***)</sup>		
Capacitance variation versus RVDC	0.1 % /V (from 0 V to RVDC)		
Equivalent Serial Inductor (ESL)	Max 100 pH		
Equivalent Serial Resistor (ESR)	Max 400 $mΩ$		
Insulation resistance	100G $\Omega$ min @ RVDC,from -55°C to +150°C		
Ageing	Negligible, < 0.001 % / 10000h		
Reliability	FIT<0.017 parts / billion hours,		
Capacitor height	Max 400 μm <sup>(*)</sup>		

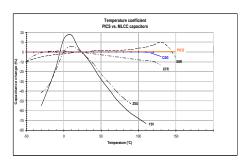


Fig.1 Capacitance change versus temperature variation compared with alternative dielectrics

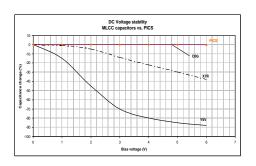


Fig.2 Capacitance change versus voltage variation compared with alternative dielectrics

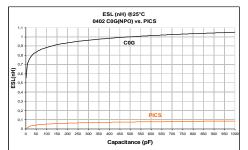
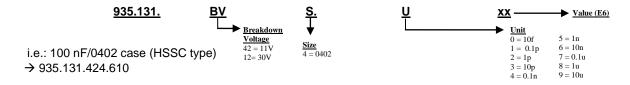


Fig.3 ESL versus capacitance value compared with alternative dielectrics

## How to order



#### **Termination and Outline**

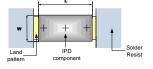
#### Termination

Lead-free nickel/solder coating compatible with automatic soldering technologies: reflow and manual

Typical dimensions, all dimensions in mm

#### Package outline

Тур.		0402
Comp.	ш	1.20±0.05
size	W	0.70±0.05



(0402 PCB footprint)

# **Packaging**

Tape and reel, tray, waffle pack or wafer delivery

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